

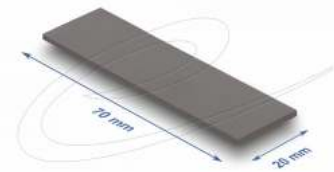
Delock Thermal Conductive Pad 70 x 20 x 1.75 mm for M.2 modules 3.2 W/mK - Low Oil Bleeding

Description

This thermal conductive pad by Delock is suitable for heat dissipation, for example, on an M.2 module. The goal of the pad is to **improve performance** and **increase the service life** of the components.

Low oil bleeding

This pad **releases very little oil**, which protects electronic components and contacts from contamination and can provide a longer lifespan. Pads with 'low oil bleeding' retain their thermal and mechanical properties better and thus ensure even and stable heat dissipation.



height 1.75 mm

Item no. 18467

EAN: 4043619184675

Country of origin: Taiwan,
Republic of China

Package: Zip poly bag

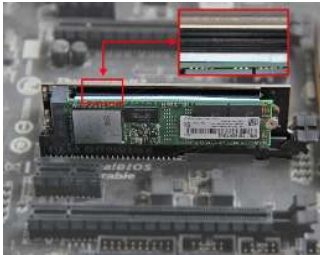
Technical details

- Thermal pad for heat dissipation
- Low oil bleeding
- Thermal conductivity: 3.2 W/mK
- Operating temperature: -60 °C ~ 180 °C
- Colour: grey
- Dimensions (LxWxH): ca. 70 x 20 x 1.75 mm

Package content

- 1 x thermal conductive pad

Images



Physical characteristics

Thermal conductivity:	3.0 W/mK
Length:	70 mm
Width:	20 mm
Height:	1.75 mm

Manufacturer information

Street	Beeskowdamm 13/15
Postal code	14167
City	Berlin
Country	Deutschland
E-Mail	info@delock.de
Website	www.delock.de